

| L Number | Hits    | Search Text   | DB  | Time stamp       |
|----------|---------|---|---|------------------|
| 1        | 4       | 646891.pn.  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/05/21 02:20 |
| 2        | 2       | 6461891.pn.   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:20 |
| 3        | 2       | 6562662.pn.   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:37 |
| 4        | 2517261 | chip die dice ic semiconductor (integrated adj circuit)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:37 |
| 5        | 251584  | (cap lid cover top) same (chip die dice ic semiconductor (integrated adj circuit))  | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:45 |
| 6        | 99254   | (cap lid cover top). with (copper cu aluminum al)   | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:46 |
| 7        | 12697   | ((cap lid cover top) with (copper cu aluminum al)) same (chip die dice ic semiconductor (integrated adj circuit))             | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:46 |
| 8        | 557     | ((cap lid cover top) with (copper cu aluminum al)) same (chip die dice ic semiconductor (integrated adj circuit))) same epoxy | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   | 2004/05/21 02:47 |